

A2 aluminum conductor an additive which suppresses the diffusion of copper, the precipitation can be prevented.

In the Claims:

Please cancel claims 5-9, 11 without prejudice.

Please amend claims 1, 2, 4 and 10 as follows:

A3
*Sub
Loy*
1. (Amended) A semiconductor device comprising a semiconductor substrate, and aluminum conductors formed on a side of a main face of the substrate which aluminum conductors comprise aluminum as a main constituent thereof, said aluminum conductors containing copper and nickel.

2. (Amended) A semiconductor device according to claim 1, wherein said aluminum conductors have at least one area in which conductor spacing is not more than 0.4 μm .

A4
4. (Amended) A semiconductor device comprising a semiconductor substrate, and aluminum conductors formed on a side of a main face of the substrate which aluminum conductors comprise aluminum as a main constituent thereof, a film adjacent to said aluminum conductors which adjacent film comprises titanium or titanium nitride as a main constituent thereof, said aluminum conductors containing copper and nickel.